Call for Papers

IEEE Transactions on Plasma Science

Special Issue on Plenary and Invited Papers from ICOPS 2015

The IEEE Transactions on Plasma Science is proud to announce a Special Issue on Plenary and Invited Papers from ICOPS 2015 to appear in the Transactions in April 2016. The Plasma Science and Applications Committee of the IEEE Nuclear and Plasma Sciences Society, along with the Guest Editors, invite contributions to this issue. The objective of this Special Issue is to provide the widest possible distribution of archival quality papers detailing the unique and innovative developments in the areas relevant to the ICOPS community and presented as Plenary and Invited Talks. Other participants in ICOPS 2015 are invited to submit a paper based on their contributions to ICOPS 2015 to the IEEE Transactions on Plasma Science and upon acceptance their manuscript will be identified as having been presented at ICOPS 2015. Contributions to the Special Issue will undergo the same rigorous review standards as typical for all IEEE Transactions and Journals.



All contributions should be submitted electronically to IEEE site "ScholarOne Manuscripts" at: http://mc.manuscriptcentral.com/tps-ieee. Further information regarding the special issue and detailed instructions for submission can be found at www.ieee.org/pubs/authors.html. Papers should be submitted to the website no later than September 1, 2015 in order to complete the review process in time for the April 2016 publication date. Plenary and Invited speakers are expected to submit a manuscript to this Special Issue.

Peer review is an important part of producing high quality journal articles. Please consider serving as a referee for our Special Issue by sending an email to one of the Guest Editors.

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